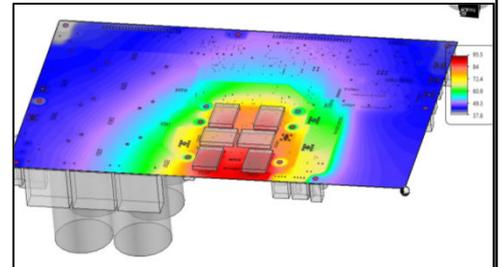


THERMAL RISK MANAGEMENT IN ELECTRONICS

TRM

Your Software for Thermal Analysis of
Printed Circuit Boards and Assemblies



Components and currents heat up the circuit board — but how hot does it get?

Are the temperature limits being observed?

Do you think to take a look at the data sheet or an Appnote is enough? ...

... Never!

No data sheet in the world can tell you the temperature for your circuit board and layout!

Why you should read this brochure?

You want to see heat, understand and improve.

You are an electrical engineer and are afraid of using finite element software and meshing.

You have no time to loose for prototyping.

You cannot delegate without extra work.

You want to delegate, but not wait forever.

You want to get started easily with defaults.

You want some expert features.

You want a fair price that includes support.

[Components ≥](#)

[Current ≥](#)

[Time dependent ≥](#)

[Technology ≥](#)

[Inductance ≥](#)

[Voltage drop ≥](#)

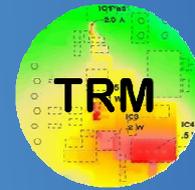
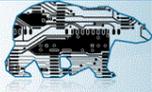
[Special setups ≥](#)

[User ≥](#)

[CAD Import ≥](#)

[Features ≥](#)

[Contact ≥](#)



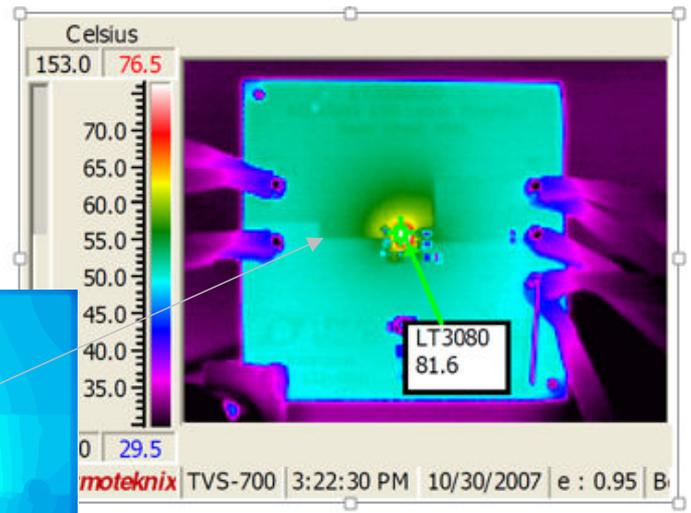
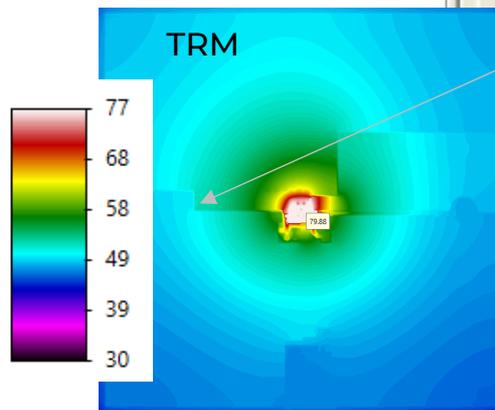
THERMAL RISK MANAGEMENT IN ELECTRONICS

> Components

TRM is calculating 3D heat spreading in the entire volume of the PCB.

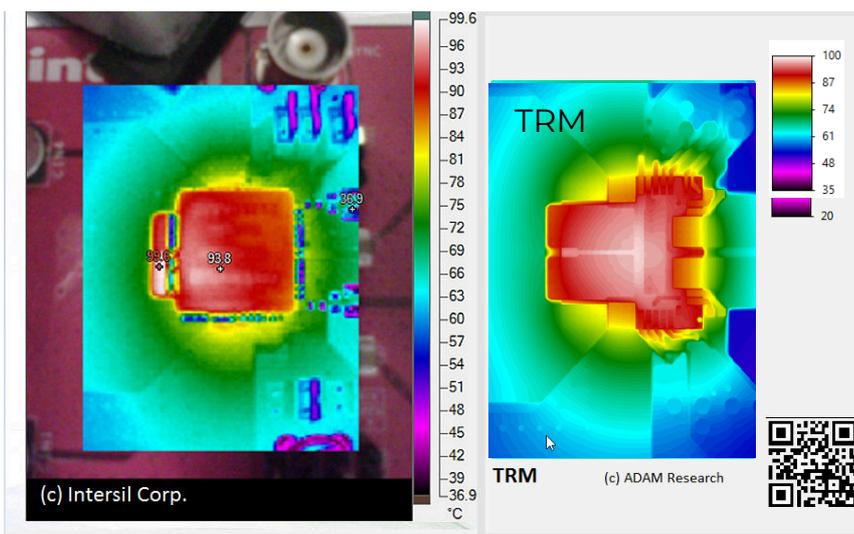
All layers, all prepregs, all via.

Consistent with measurement - without CAD model of the component.



<https://www.analog.com/media/en/dsp-documentation/evaluation-kit-manuals/dc995A.pdf>

Cooling by convection, heat sink or cold plate

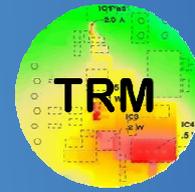
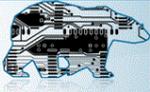


Material data is stored in a customizable material database

How much power loss leads to what temperature?

What temperature corresponds to what power loss?

<http://www.intersil.com/content/dam/Intersil/documents/an19/an1922.pdf>
https://www.adam-research.de/pdfs/TRM_CaseStudy1.pdf

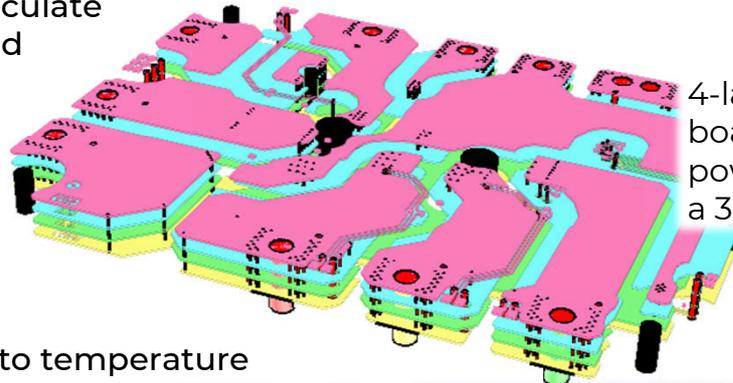


THERMAL RISK MANAGEMENT IN ELECTRONICS

> Current

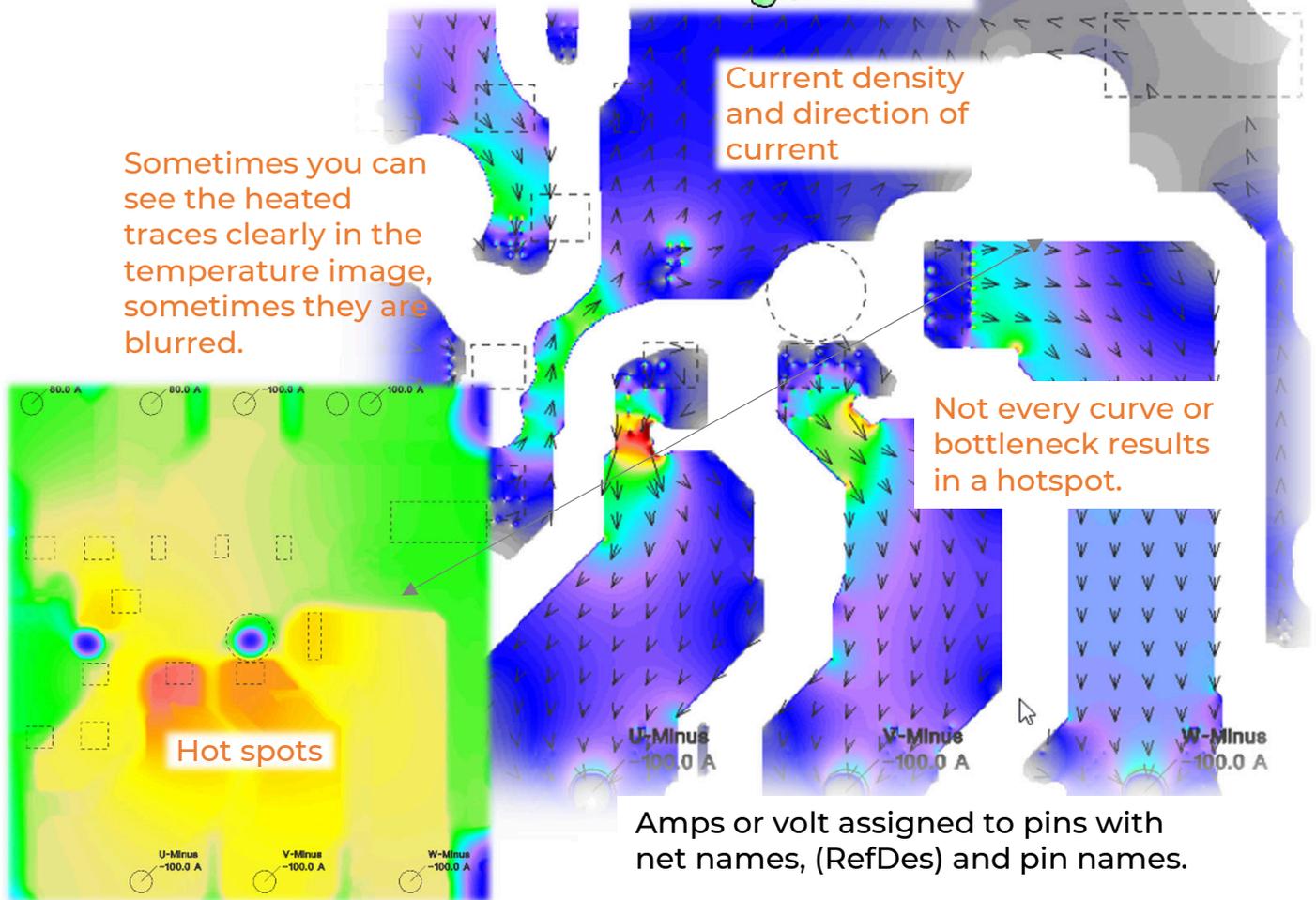
Electric current creates local heat (Joule).

TRM takes amp or volt settings to calculate DC voltage and current.

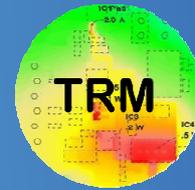
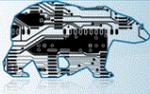


4-layer printed circuit board module for power distribution to a 3-phase motor

From current to temperature



Amps or volt assigned to pins with net names, (RefDes) and pin names.



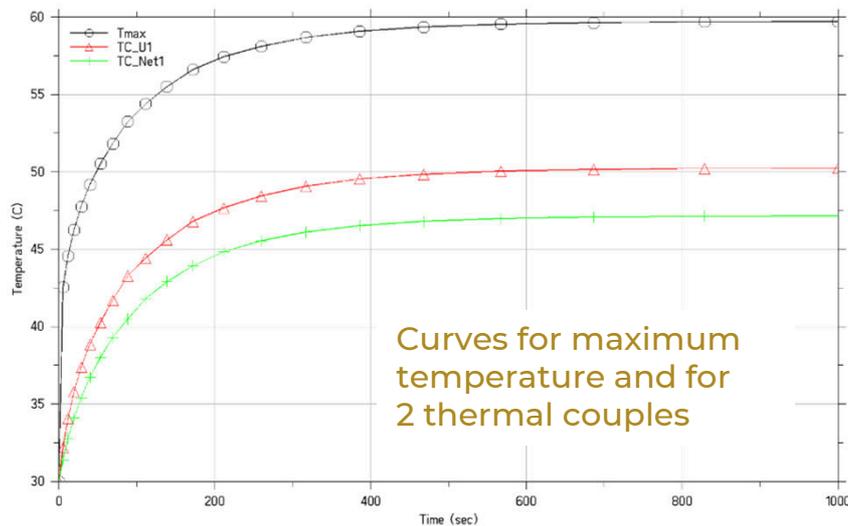
THERMAL RISK MANAGEMENT IN ELECTRONICS

> Transient

TRM can calculate the time-dependent heating or cooling behavior. Either use constant current and heat sources or supply time profiles in a file. A wizard menu helps to select the time steps.

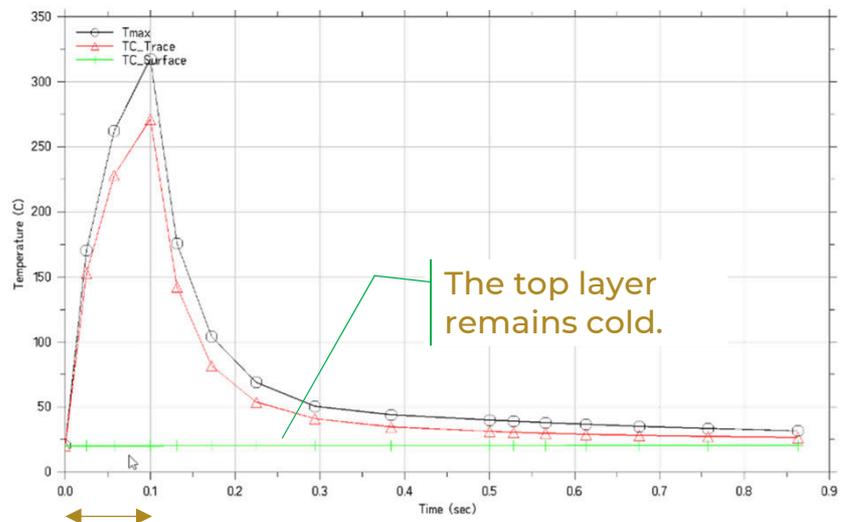
Pictures and thermal couples record the transient and store it.

Heating curve with permanent losses.

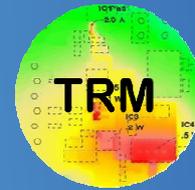
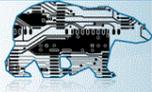


Curves for maximum temperature and for 2 thermal couples

100 ms current surge in inner layer



100 milliseconds is not enough time for the heat wave to reach the surface and be detected by instruments.



THERMAL RISK MANAGEMENT IN ELECTRONICS

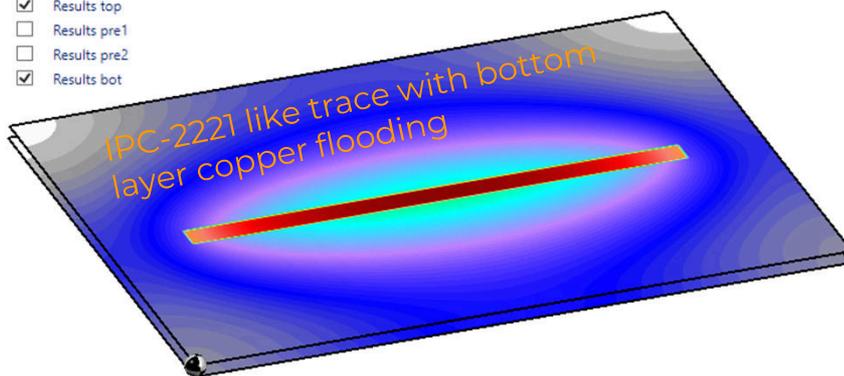
> Technology

TRM can be used for purely technological investigations.

Even without layout data.

Create traces, planes and circles by keyboard and coordinates. or feed rectangles and circles graphically or from ASCII files.

- Results top
- Results pre1
- Results pre2
- Results bot



Materials database

Add entry
Copy entry

Delete entry
Save Database

FR4\$TRM
 Cu\$TRM
 Comp_diel_loc\$TRM
 Comp_diel_hic\$TRM
 Comp_diel_vhc\$TRM
 perfectEI\$TRM
 Ignore\$TRM
 Al\$TRM
 Al_diel
 R1566\$TRM

Name

Tc1 (°C)

Tconx (W/mK)

Tconz (W/mK)

Deeper analysis with tables

Report by levels

| | |
|-------------------|---------|
| 1 Top Layer | 0.088 W |
| 2 Dielectric | 0.000 W |
| 3 Mid Layer 1 | 0.020 W |
| 4 Dielectric | 0.001 W |
| 5 Mid Layer 2 | 0.014 W |
| 6 Dielectric | 0.000 W |
| 7 Bottom Layer | 0.004 W |
| Total Joule Heat= | 0.127 W |

Report of Electric Results per Net

| Net | Flux(A)>0 | Vmin(V) | Vmax(V) | Vdrop(mV) | RDC(mOhm) | PJoule(W) |
|------------|-----------|---------|---------|-----------|-----------|-----------|
| 1 AGND | 10.000 | 0.000 | 0.013 | 12.960 | 1.296 | 0.127 |
| Total Heat | | | | | | 0.127 |

Batch runs

Project Build Board Test it Results Extra Batch 3D

Start Cancel

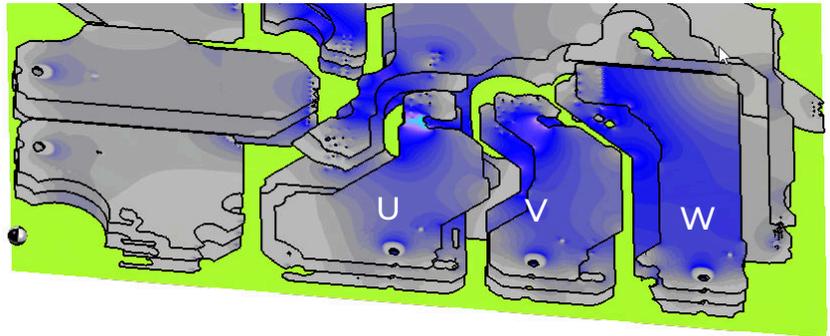
| | Table | Index | Name | Column | Current value | Batch values |
|-------------------------------------|-------|-------|----------|--------|---------------|---------------------|
| <input checked="" type="checkbox"/> | Loads | 2 | net1~IN | Ampere | -11 | -9.00;-13.00;-15.00 |
| <input checked="" type="checkbox"/> | Loads | 3 | net1~OUT | Ampere | 11 | 9.00;13.00;15.00 |



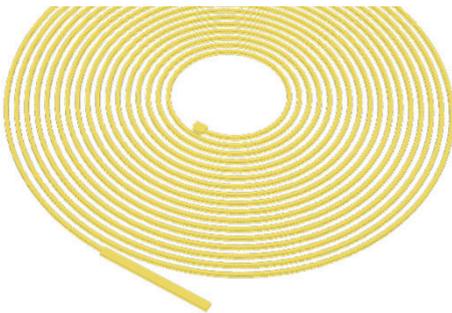
THERMAL RISK MANAGEMENT IN ELECTRONICS

> Inductance (Inductivity)

Self inductance and mutual inductance depend on the shape of traces and the 3D flow of current.



TRM: 6.0 μH
EM software: 5.9 μH
Measured: 5.07 μH

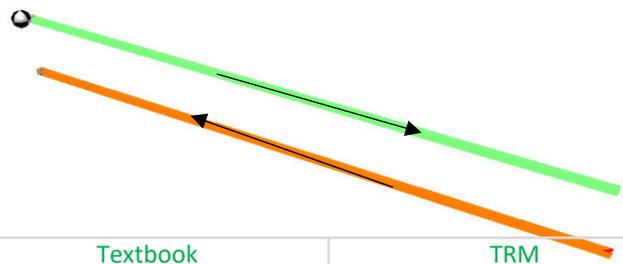
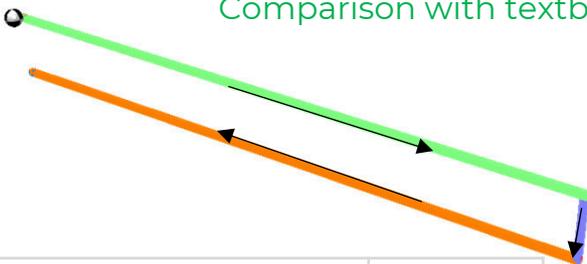


TRM calculates L values precisely from the electric flow pattern.

$$\mathbf{L} = \begin{pmatrix} 9.4 & 5.1 & -7.4 \\ 5.1 & 17 & -5.7 \\ -7.4 & -5.7 & 38 \end{pmatrix} \text{ nH}$$

Inductance matrix for phases (U,V,W)

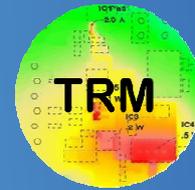
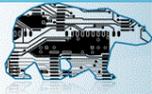
Comparison with textbook



| Textbook Dual line | TRM |
|--|--------------------|
| $L \approx \frac{\mu\ell}{4\pi} (1 + \ln(\frac{d-a}{a})) = 128 \text{ nH}$ | $L=122 \text{ nH}$ |

| Textbook Single line | TRM |
|--|---|
| $L_{self} \approx \frac{\mu\ell}{2\pi} (\ln(\frac{2\ell}{w+t}) + \frac{1}{2}) = 102$ | $L_{11}=L_{22} = 102 \text{ nH}$ |
| | Self- and mutual inductance $\mathbf{L} = \begin{pmatrix} 102 & -41 \\ -41 & 102 \end{pmatrix} \text{ nH}$ |
| | Total of matrix elements $102+102-41-41= 122 \text{ nH}$ |

Dual line
 $L \approx \frac{\mu\ell}{4\pi} (1 + \ln(\frac{d-a}{a})) = 128 \text{ nH}$

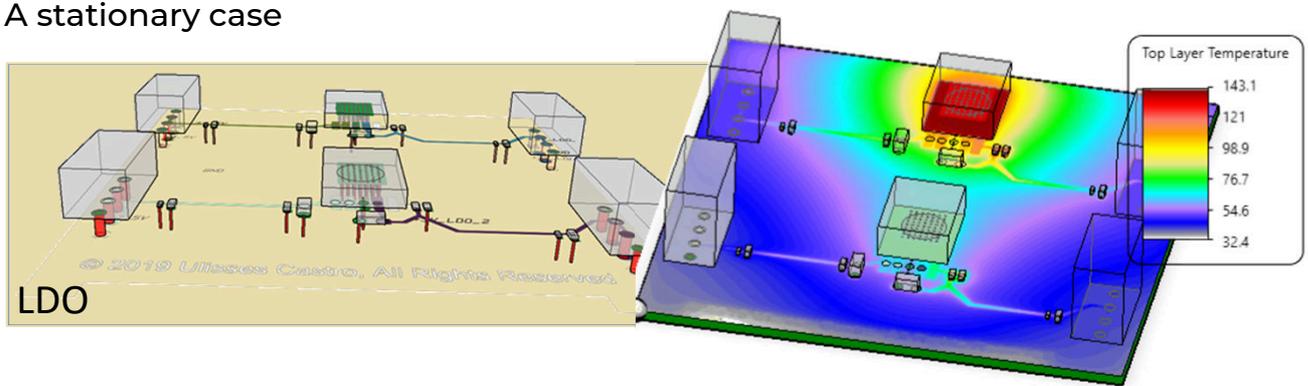


THERMAL RISK MANAGEMENT IN ELECTRONICS

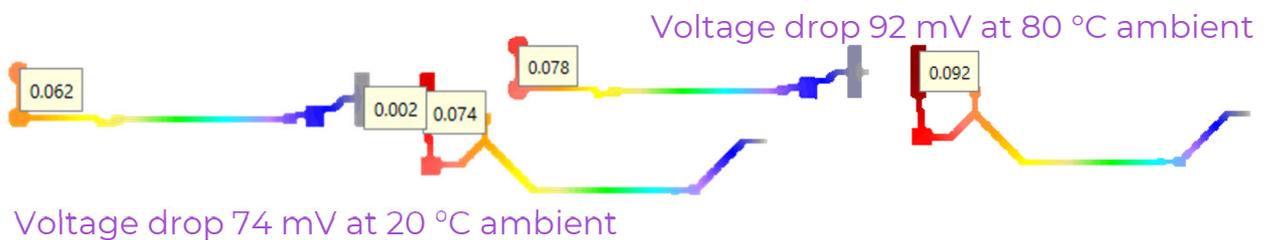
> Voltage Drop and Temperature

The electrical resistance of copper depends on temperature.
TRM can take it into account.

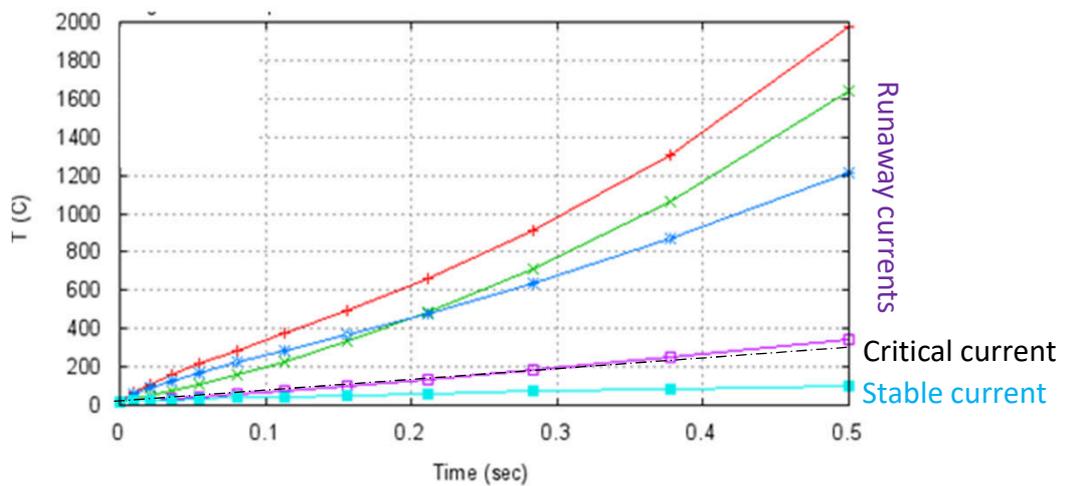
A stationary case

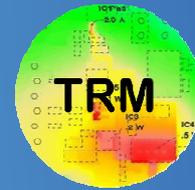
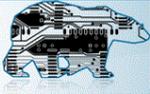


LDO



A thermal runaway event if a critical current is exceeded



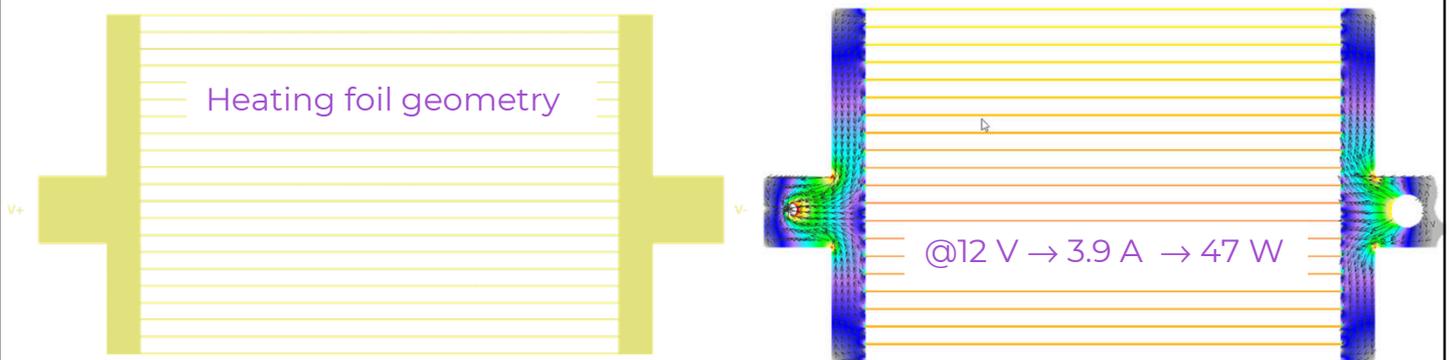


THERMAL RISK MANAGEMENT IN ELECTRONICS

> Special Setups

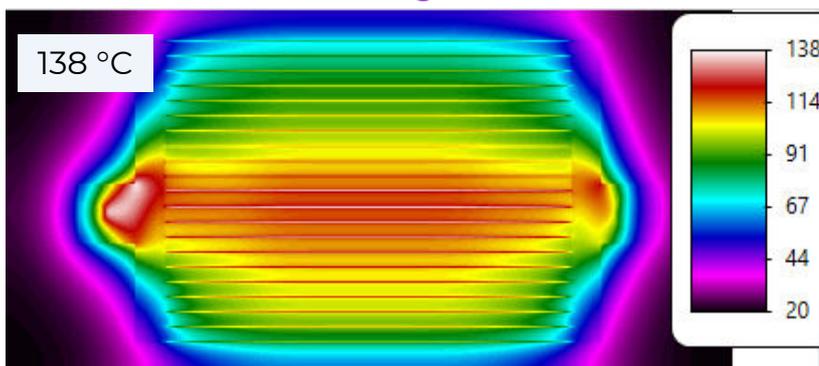
Practitioners who want to see how surfaces heat but are not interested in circuit boards or electronics can prepare conducting patterns using 2D drawing programs and import them from bitmaps.

Then they are ready to simulate.



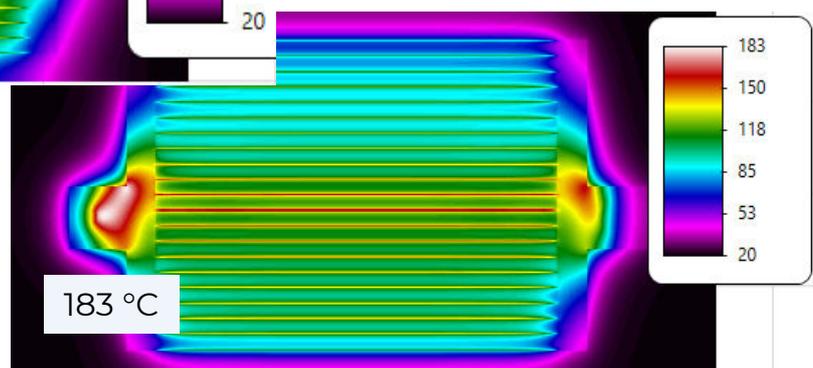
Heating foil on substrates
(from bitmap sketch)

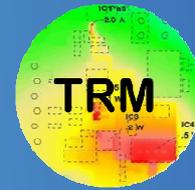
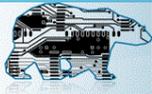
Foil on 0.5 mm glass substrate



This design proposal
does not seem to be
the best solution.

Foil on 0.5 mm plastics substrate





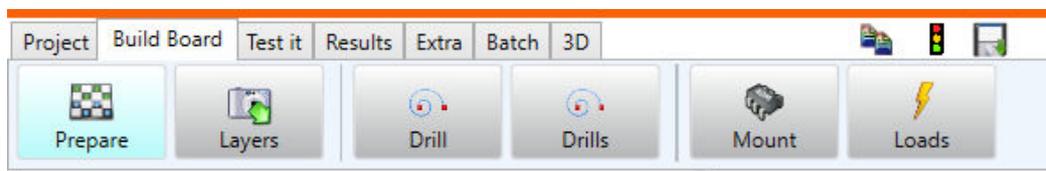
THERMAL RISK MANAGEMENT IN ELECTRONICS

> User Actions

TRM offers a lot for both thermal beginners and thermal experts.

TRM is *not* intended to be an integrated tool.

Add files of your choice from multiple data sources.



Fill tables and Edit.

English, German, traditional & simplified Chinese.

| | Level | Name | Type | File | View | FR4 white | Thick (um) | Conductor | Dielectric |
|-----|-------|--------|------|---------------|------|-------------------------------------|------------|-----------|------------|
| + x | 1 | Top | ger | copper_11.gbr | View | <input checked="" type="checkbox"/> | 35 | Cu\$TRM | FR4\$TRM |
| + x | 2 | Pre1 | pre | | View | <input checked="" type="checkbox"/> | 1500 | Cu\$TRM | FR4\$TRM |
| + x | 3 | Bottom | ger | copper_12.gbr | View | <input checked="" type="checkbox"/> | 35 | Cu\$TRM | FR4\$TRM |

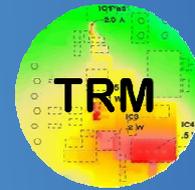
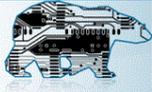
Drop down menus for many actions

- Color
- Change cell values
- Copy
- Paste
- Copy row(s)
- Paste row(s)
- Duplicate row

| Drillfile | View | Tech |
|--------------------------|------|------|
| Arduino_MEGA2560_ref.drd | View | TH C |

Table with Amps and Watts

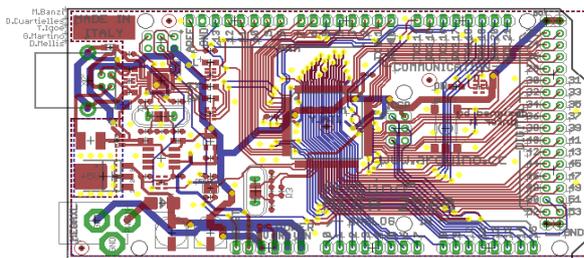
| | Index | Name | PosX | PosY | Di | Di | Hi | Be | Er | M | Form | K/W-board | K/W-air | Watt | Celsius | Ampere | Volt |
|-----|-------|-------------|-------|-------|-----|----|----|----|----|-----|------|-----------|---------|------|---------|--------|------|
| + x | 345 | PL6~XIOL-11 | 96.52 | 22.86 | 1.2 | -1 | 2 | 1 | 99 | Cu! | c | -1 | -1 | | 0 | | |
| + x | 346 | PL7~IC3-42 | 52.8 | 20.35 | 0.2 | -1 | 2 | 1 | 1 | Cu! | c | -1 | -1 | | 1 | | |
| + x | 347 | PL7~XIOL-12 | 93.98 | 22.86 | 1.2 | -1 | 2 | 1 | 99 | Cu! | c | -1 | -1 | | -1 | | |
| + x | 348 | PWRIN~D1-A | 16.21 | 12.07 | 1.9 | -1 | 2 | 1 | 1 | Cu! | c | -1 | -1 | | 0 | | |
| + x | 349 | PWRIN~X1-2 | 11.68 | 8.31 | 3.8 | -1 | 2 | 1 | 99 | Cu! | c | -1 | -1 | | 0 | | |
| + x | 350 | RD+~IC4-29 | 15.99 | 37.85 | 0.2 | -1 | 2 | 1 | 1 | Cu! | c | -1 | -1 | | 0 | | |



THERMAL RISK MANAGEMENT IN ELECTRONICS

> CAD Import 1/4

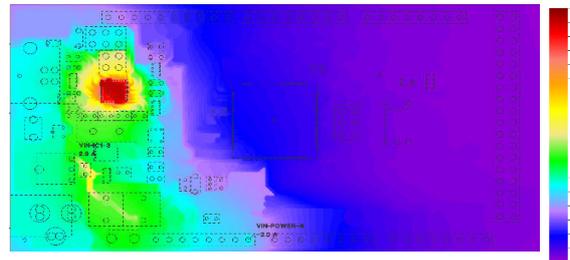
From design ...



Arduino Mega 2560 Reference Design

Reference Designs ARE PROVIDED "AS IS" AND "WITH ALL FAULTS". ARDUINO DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, INCLUDING PRODUCTS INCLUDING BUT NOT LIMITED TO, ANY IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. Arduino may make changes to specifications and product descriptions at any time, without notice. The Customer must not rely on the absence, or characteristics of any features or instructions marked "reserved" or "untested". Arduino reserves these for future definition and shall have no responsibility whatsoever for conflicts or inconsistencies arising from future changes to them. The product information on the web site or materials is subject to change without notice. Do not finalize a design with this information.

... to result in a minute or two.



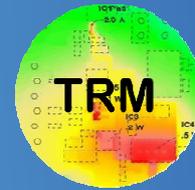
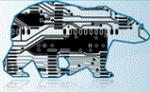
TRM offers a bunch of import „Wizards“

| | | |
|-----------------|--|---|
| Altium | <p>Associated scripts are available to output the data in a controlled format.</p> | Help TRM |
| Allegro + OrCAD | | Help TRM |
| Eagle | | ULP Run ULP |
| Zuken | | TRM3 Export Settings TRM3 Export Data TRM3 Interaktiv TRM3 Thermal Risk Management Tools |
| Pulsonix | | TRM TRM... |

A wizard fills the major tables: Layers, Drill, Mount and Loads and completes the import process automatically .

If they wish, users of other CAD systems can create simplified templates themselves and use them to fill in the tables.

All data can be manually changed and supplemented after import



THERMAL RISK MANAGEMENT IN ELECTRONICS

> CAD Import 2/4

Some scripts can also export attribute values: net names and pins with electrical attributes, as well as components with thermal values.

Pulsonix



Components

0.1 W on each LED

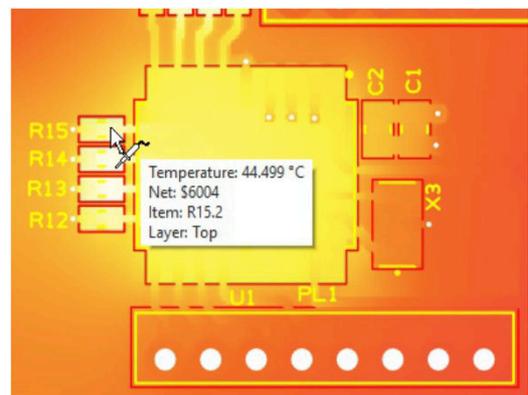
| Name | Part Name | Description | Family | Footprint | <Component Height> | Category | TRM-POWER |
|------|------------|-------------------|---------|-----------|--------------------|----------|-----------|
| LED1 | KP-2012PBC | LED SMD CHIP BLUE | KP-2012 | LED2x1.25 | 1.1mm | Led | 0.1 |
| LED2 | KP-2012PBC | LED SMD CHIP BLUE | KP-2012 | LED2x1.25 | 1.1mm | Led | 0.1 |
| LED3 | KP-2012PBC | LED SMD CHIP BLUE | KP-2012 | LED2x1.25 | 1.1mm | Led | 0.1 |
| LED4 | KP-2012PBC | LED SMD CHIP BLUE | KP-2012 | LED2x1.25 | 1.1mm | Led | 0.1 |
| LED5 | KP-2012PBC | LED SMD CHIP BLUE | KP-2012 | LED2x1.25 | 1.1mm | Led | 0.1 |
| LED6 | KP-2012PBC | LED SMD CHIP BLUE | KP-2012 | LED2x1.25 | 1.1mm | Led | 0.1 |

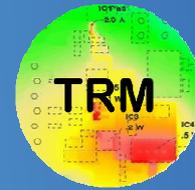
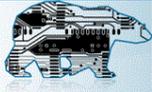
Pins and Nets

1.2 A on each signal

| Name | Pin | Net | TRM-VALUE |
|------|-----|--------|-----------|
| Q1 | 1 | feedP7 | -1.2A |
| Q2 | 1 | feedP6 | -1.2A |
| Q3 | 1 | feedP5 | -1.2A |
| Q4 | 1 | feedP4 | -1.2A |
| Q5 | 1 | feedP3 | -1.2A |
| Q6 | 1 | feedP2 | -1.2A |
| Q7 | 1 | feedP1 | -1.2A |
| Q8 | 1 | feedP | -1.2A |
| LED1 | 1 | feedP | 0.1A |
| LED2 | 1 | feedP | 0.1A |
| LED3 | 1 | feedP | 0.1A |
| LED4 | 1 | feedP1 | 0.1A |
| LED5 | 1 | feedP1 | 0.1A |
| LED6 | 1 | feedP2 | 0.1A |

Pulsonix is also able to import and to visualize TRM results



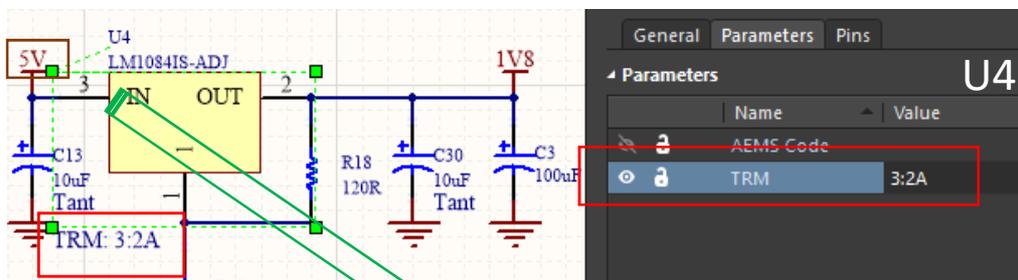


THERMAL RISK MANAGEMENT IN ELECTRONICS

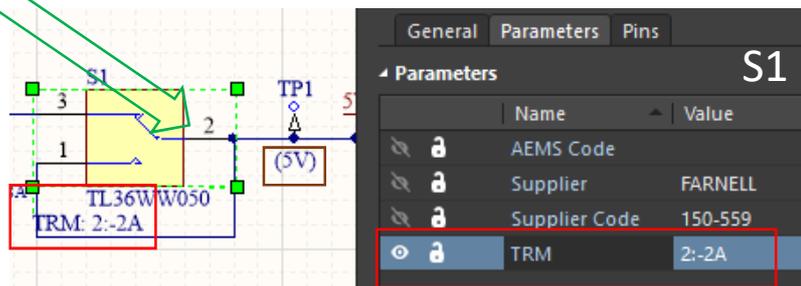
> CAD Import 3/4

Altium Designer

Values in schematics ...



2 A in net „5V“
from U4-3 to S1-2

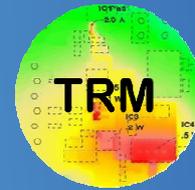


... or with Parameter Manager

Parameter Table Editor For Project [SL1 Xilinx Spartan-1IE PQ208 Rev1.01.P]

| Object Type | Document | Identifier | TRM | AEMS Code | Capacitor Type |
|-------------|-------------------------|------------|-----------------|-----------|----------------|
| Part | SL_Power.SchDoc | R13 | 1:100mA;5mR | 1200781 | |
| Part | SL_Power.SchDoc | U3 | 1.3W;1:0.1A | | |
| Part | SL_Power.SchDoc | R14 | 2:0V;1.4R | 1200012JT | |
| Part | SL_Power.SchDoc | S1 | 2:5A | | |
| Part | SL_LCD_SW_LED_2E.SchDoc | LCD1 | 2:-2.5A;15:-2A5 | | |
| Part | SL_Power.SchDoc | R12 | 100mR | 1200012JT | |

| Object Type | Document | Identifier | GENERATED_N... | TRM | trm-power |
|-------------|------------------------|------------|----------------|-----|-----------|
| Pin | SL_FPGA_Auto_2E.SchDoc | U1-119 | VCCINT | 1A | |
| Pin | SL_FPGA_Auto_2E.SchDoc | U1-12 | GND | 0V | |
| Pin | SL_FPGA_Auto_2E.SchDoc | U1-120 | FPGA_PS | | |

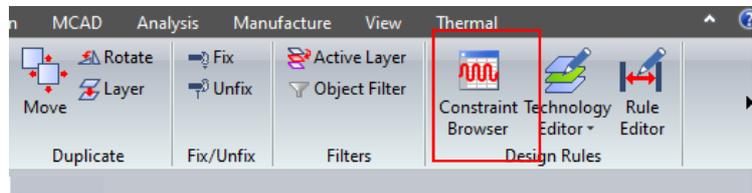


THERMAL RISK MANAGEMENT IN ELECTRONICS

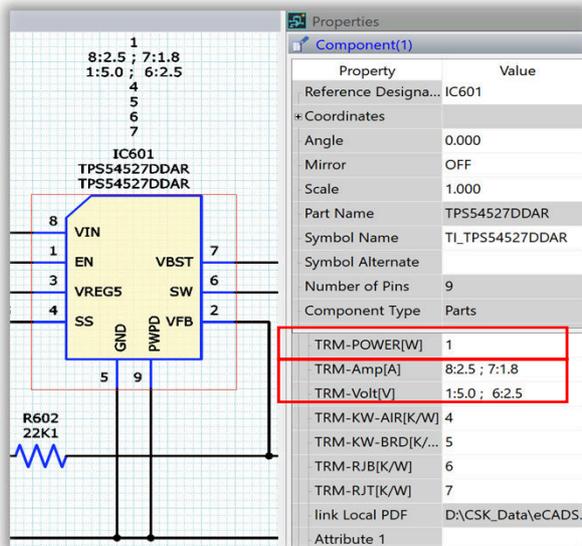
> CAD Import 4/4

ZUKEN e-CADSTAR

Use Schematic Editor and Constraint Browser



Schematic Editor

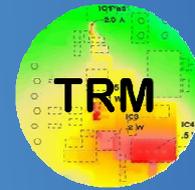
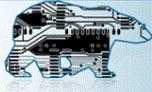


Constraint Browser

Electric Thermal

| Component | Selected | TRM-Amp[A] | TRM-KW-AIR[K/W] | TRM-KW-BRD[K/W] | TRM-POWER[W] | TRM-RIRIK[M] |
|-----------|----------|------------|-----------------|-----------------|--------------|--------------|
| E1 | E1 | 1:~3:2~2 | | | 0 | |
| IC103 | IC103 | | | | 0.1 | |
| IC104 | IC104 | | | | 0.1 | |
| IC204 | IC204 | | | | 0.2 | |
| IC404 | IC404 | | | | 0.3 | |
| IC201 | IC201 | | | | 0.4 | |
| IC2 | IC2 | | | | 0.4 | |
| IC3 | IC3 | | | | 0.4 | |
| IC4 | IC4 | | | | 0.4 | |
| IC6 | IC6 | | | | 0.4 | |
| IC601 | IC601 | | | | 0.5 | |
| IC500 | IC500 | | | | 0.5 | |
| IC501 | IC501 | | | | 0.5 | |
| IC502 | IC502 | | | | 0.5 | |
| IC503 | IC503 | | | | 0.5 | |
| IC504 | IC504 | | | | 0.5 | |
| IC505 | IC505 | | | | 0.5 | |
| IC506 | IC506 | | | | 0.5 | |
| IC507 | IC507 | | | | 0.5 | |
| IC508 | IC508 | | | | 0.5 | |
| IC509 | IC509 | | | | 0.5 | |
| IC102 | IC102 | | | | 0.9 | |
| IC401 | IC401 | | | | 0.11 | |
| IC205 | IC205 | | | | 0.12 | |
| IC101 | IC101 | | | | 0.12 | |
| IC403 | IC403 | | | | 0.25 | |
| IC1 | IC1 | | | | 3.75 | |
| CN2 | CN2 | 2:3:1:2 | | | | |
| 0 | 0 | | | | | |
| 1 | 1 | | | | | |

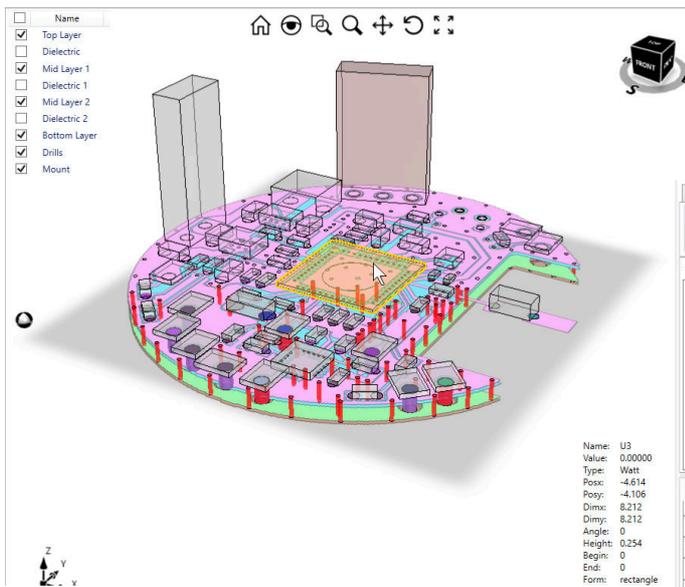
Forward - Backward annotation.



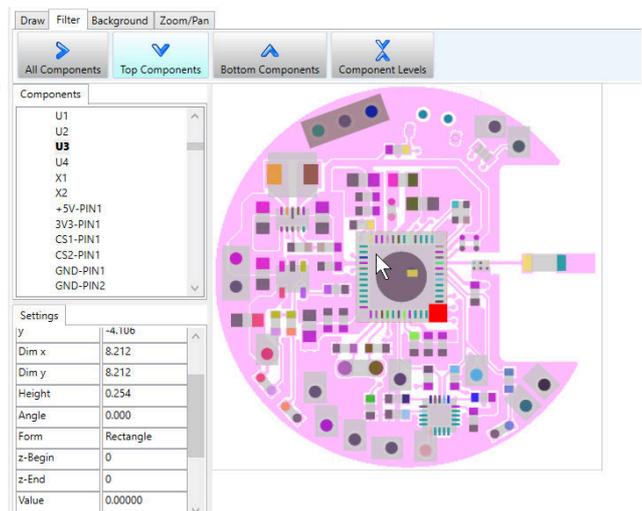
THERMAL RISK MANAGEMENT IN ELECTRONICS

> CAD Import 5/5

Check import data in 3D ...



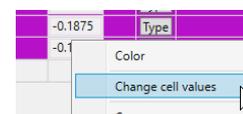
... and 2D

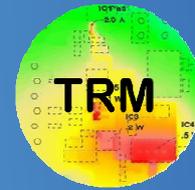
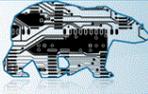


... or manipulate (move, delete, copy, add/remove values or materials, ...)

watt>0 or ampere<>d

| | Index | Name | PosX (mm) | PosY (mm) | DimX (mm) | DimY (mm) | Ht | Be | Er | Material | Form | K/ | K/ | Watt | Celsius | Ampere | Volt | Type |
|--|-------|------------|-----------|-----------|-----------|-----------|-----|----|----|----------|------|----|----|------|---------|---------|------|------|
| | 61 | U3 | -4.614 | -4.106 | 8.212 | 8.212 | 0.2 | 0 | 0 | Comp_di | r | -1 | -1 | 2.3 | | | | Type |
| | 286 | +3V3~3V3-1 | -7.239 | -13.462 | 1.12 | -1 | 2 | 1 | 1 | Cu\$TRM | c | -1 | -1 | | | 1.5 | | Type |
| | 307 | +3V3~U3-1 | -3.355 | -3.765 | 0.194 | 0.728 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |
| | 308 | +3V3~U3-20 | 2.529 | 0.653 | 0.728 | 0.194 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |
| | 309 | +3V3~U3-23 | 2.529 | 2.153 | 0.728 | 0.194 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |
| | 310 | +3V3~U3-34 | -2.355 | 3.037 | 0.194 | 0.728 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |
| | 311 | +3V3~U3-35 | -2.855 | 3.037 | 0.194 | 0.728 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |
| | 312 | +3V3~U3-40 | -4.273 | 1.153 | 0.728 | 0.194 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |
| | 313 | +3V3~U3-48 | -4.273 | -2.847 | 0.728 | 0.194 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |
| | 314 | +3V3~U3-8 | 0.145 | -3.765 | 0.194 | 0.728 | 2 | 1 | 1 | Cu\$TRM | r | -1 | -1 | | | -0.1875 | | Type |





THERMAL RISK MANAGEMENT IN ELECTRONICS

Precision by Physics and Geometry

TRM3.10 Feature summary

Input

- Individual Gerber and drill files
- Your own drawings
- Manual actions (similar to Excel) and file import
- Import Wizards for Allegro, Altium, Eagle, e-CADSTAR, Pulsonix

Analysis modes

- Field calculation in all layers and prepregs in high resolution
- Trace heating (Ampacity) and component heating
- DC Voltage drop and flow of current in requested traces
- Steady state and transient
- Switching states (current by time or phase interval)
- Temperature dependent material properties
- Inductance Matrix
- Batch runs

Selective environmental conditions

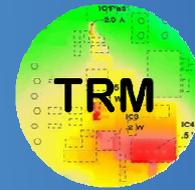
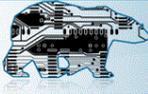
- Convection Cooling
- Conduction cooling and heat sinks
- Radiation into vacuum
- Combinations

Results

- 2D diagrams, 3D exploded view
- Tables of results
- Efficient computation times even on large designs

Licensing

- Floating licenses on the user company's license server.
- No external data transfer.



THERMAL RISK MANAGEMENT IN ELECTRONICS

TRM is more than just software.

Software can help you ...

... by watching results and experimenting you will learn a lot about your board and the technologies you used

- ❖ How to do thermal PCB design
- ❖ Weak points
- ❖ Alternatives
- ❖ Savings potential
- ❖ Ideas for the next design

Beyond that

- ❖ See and understand Thermal Management
- ❖ Test the benefits of new thermal products
- ❖ Learn how to read and evaluate data sheets, application notes, and advertisements.

More examples

Videos: <https://www.youtube.com/@adamresearch-thermalriskma7955/videos>

Linkedin: www.linkedin.com/in/johannes-adam-ab4991123

Contact for a trial installation

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www.adam-research.com

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